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(30) Priority:	04.11.99 KR 1999 9948592	(71) Applicant: SAMSUNG ELECTRONICS CO LTD
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**(54) MANUFACTURING
METHOD OF MEMS
STRUCTURE ENABLING
WAFER LEVEL VACUUM
PACKAGING**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a manufacturing method of an MEMS structure enabling wafer level vacuum packaging.

SOLUTION: This method includes: a first step of forming on a first wafer a laminated layer of a multilayered structure including a signal line, a second step of attaching a second wafer to the laminated layer of the multilayered structure, a third step of grinding the first wafer to a predetermined thickness, a fourth step of forming on the first wafer an MEMS structure connected to the signal line and positioned inside a vacuum region and a pad positioned outside the vacuum region, a fifth step of forming on a third wafer a structure having a space corresponding to the vacuum region of the MEMS structure, and a sixth step of combining the ground surface of the first wafer with the third wafer in a vacuum environment.

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